

WD3609DC

800mA Buck/Boost Charge Pump Flash LED Driver

Description

The WD3609DC is a current-regulated charge pump ideal for powering high brightness LEDs for camera flash applications. The charge pump can be set to regulate two current levels for FLASH and TORCH modes.

The WD3609DC automatically switches modes between step-up and step-down ensuring that LED current does not depend on the forward voltage. It switches at 2.4MHz, allowing the use of tiny components. The supply voltage ranges from 2.7V to 5.5V and is ideally suited for all applications powered by a single LI-lon battery cell or three to four NiCd, NiMH, or Alkaline battery cells.

The WD3609DC also features a very low shutdown current, an automatic soft-start mode to limit inrush current, as well as over current, over voltage and over-Thermal shutdown control.

A low current sense reference voltage (50mV) allows the use of small 0603 current sensing resistors.

The WD3609DC is available in Green DFN3x3-10L package and is specified over an ambient temperature range of -40 $^{\circ}$ C to +85 $^{\circ}$ C.

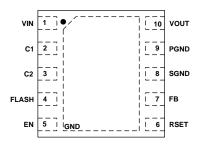
Features

- Output Current up to 800mA
- Up to 95% Efficiency in Torch Mode
- Adjustable FLASH Mode Current
- Automatic Buck/Boost Mode Switchover
- Wide Input Voltage Range: 2.7V to 5.5V
- Minimum External Components: No Inductors
- High Frequency Operation: 2.4MHz
- Low 50mV Reference for Low Loss Sensing
- PWM Dimming Control
- Automatic Soft Start Limits Inrush Current
- Low Ripple and EMI

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DFN3x3-10L



Pin configuration (Top view)



WD3609DC

3609DC = Device code Y = Year code W = Week code Marking

Order Information

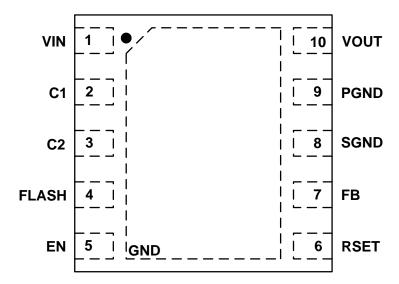
Device	WD3609DC-10/TR	
Function	With timeout	
Package	DFN3x3-10L	
Shipping	3000/Reel&Tape	

Applications

- Cellphones
- PADs



Pin configuration (Top view)



Pin descriptions

Symbol	DFN3x3-10L	Descriptions					
VIN	1	Input voltage for the charge pump. Decouple with 4.7μF or 10μF ceramic					
VIIN	1	capacitor close to the pins of the IC.					
C4	2	Positive input for the external flying capacitor. Connect a ceramic 1µF					
C1	2	capacitor close to the pins of the IC.					
	2	Negative input for the external flying capacitor. Connect a ceramic 1µF					
C2	3	capacitor close to the pins of the IC.					
		Logic input to toggle operation between FLASH and TORCH mode. In					
		TORCH mode FB is regulated to the internal 50mV reference. In FLASH					
FLASH	4	mode FB reference voltage can be adjusted by changing the resistor from					
		R_{SET} pin to ground. Choose the external current sense resistor (R_{SENSE}) based					
		on desired current in TORCH mode and Flash mode.					
Shutdown control input. Connect to VIN for normal operation, control input. Shutdown control input. Connect to VIN for normal operation, control input.							
						after the VIN has settled if the VIN ramping up is slow.	
		Connect a resistor from this pin to ground. When in FLASH mode (FLASH =					
R _{SET}	6	High) this resistor sets the current regulation point according to the following:					
		VFB = $(1.26V / R_{SET})x11.2k\Omega$					
FB	7	Feedback input for the current control loop. Connect directly to the current					
1.0	,	sense resistor.					
SGND	8	Internal ground pin. Control circuitry returns current to this pin.					
PGND	9	Power ground pin. Flying capacitor current returns through this pin.					
Charge Pump Output Voltage. Decouple		Charge Pump Output Voltage. Decouple with an external capacitor. At least					
VOUT	10	1μF is recommended. If Higher value capacitor is used, output ripple					
smaller.							



Typical applications

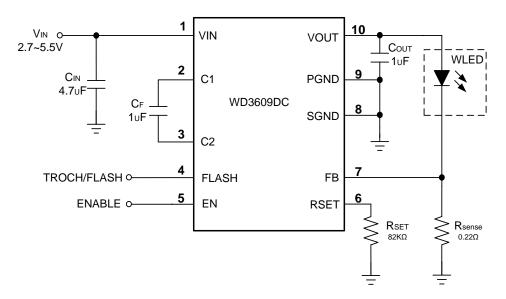


Figure 1. Single LED flash circuit @ 800mA flash current

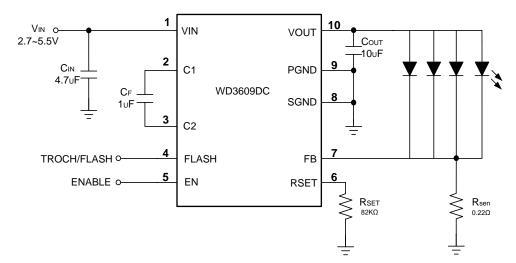
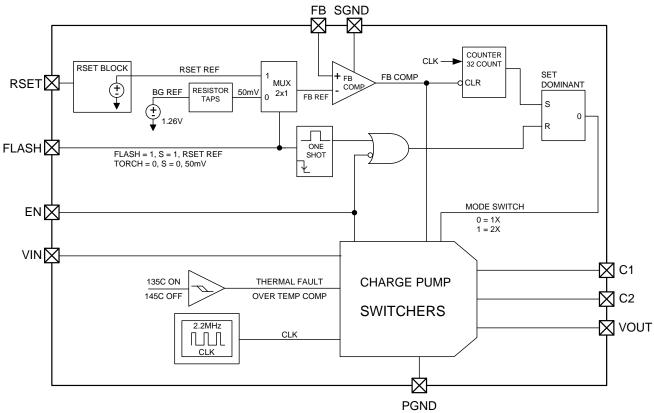


Figure 2. Multiple LED flash circuit @800mA flash current

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Block diagram



Absolute maximum ratings

Parameter	Symbol	Value	Unit
VIN,VOUT pin voltage range	V	-0.3∼6	V
EN, FB pin voltage range	-	-0.3~5.5	V
Output Current Pulse(Flash)	I _{O(Flash)}	1.5	А
Output Current Continuous(Torch)	I _{O(Torch)}	0.4	А
Power Dissipation (Note 1)		3	W
Junction to Ambient Thermal Resistance (Note 1)	$R_{ heta JA}$	57	°C/W
Junction temperature	T _J	150	°C
Lead temperature(Soldering, 10s)	T∟	260	°C
Operating ambient temperature	Topr	-40 ~ 85	°C
Storage temperature	Tstg	-55 ~ 150	°C
ESD Patings	НВМ	8000	V
ESD Ratings	MM	400	V

These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Note 1: Surface mounted on FR-4 Board using 1 square inch pad size, dual side, 1oz copper



Electronics Characteristics

(Full= -40 $^{\circ}$ C to +85 $^{\circ}$ C , V_{IN}= 3.6V, C_{IN} = 4.7uF, C_F = C_{OUT} = 1uF, V_{EN}= V_{IN}, typical values at +25 $^{\circ}$ C, unless otherwise noted)

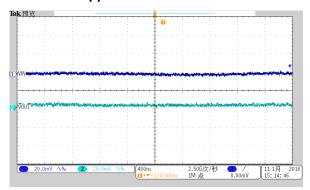
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Voltage Range	V _{IN}		2.7		5.5	V
Outles and Comment	IQ	V _{IN} =2.7V-5.5V FLASH=GND,		0.3		mA
Quiescent Current	ΙQ	1X Mode I _{LOAD} =100uA FLASH = High, 2x mode		2		mA
Shutdown Supply Current	I _{SHDN}	$V_{EN} = 0V, V_{IN} = 5.5V$			1	uA
Feedback reference	V_{FB}	FLASH = V_{IN} , $R_{SET} = 82k\Omega$	163	170	187	mV
Voltage	V FB	FLASH = GND	45	50	55	mV
FB Pin Current	I _{FB}	$V_{FB} = 0.3V$			1	uA
Oscillator Frequency	f _{OSC}			2.4		MHz
Charge Pump Equivalent		V _{IN} = 3.6V		0.8	1	Ω
Resistance (1x mode)		V _{IN} = 3.0 V		0.8	'	32
Charge Pump Equivalent				5		Ω
Resistance (2× mode)				3		32
EN, FLASH Logic Low	V _{EN,FLASH} H				0.4	V
EN, FLASH Logic High	V _{EN,FLASH L}		1.3			V
EN, FLASH Pin Current	I _{EN,FLASH}				1	uA
V _{OUT} Turn-on Time		V_{IN} = 3.6V, FB within 90% of regulation		250		us
Thermal Shutdown	Т			150		°C
Temperature	T _{SHDN}			130		
Maximum Flash ON time		V _{IN} = 3.6V	0.8	1.2	1.6	S
Current Limit	I _{limit}	V _{IN} =3.6 V	0.85	1.2	1.5	Α

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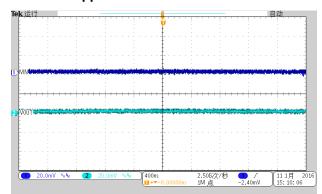


Typical Characteristics (Ta=25°C, C_{IN} = 4.7uF, C_{OUT} = 4.7uF, C_F=1uF, unless otherwise noted)

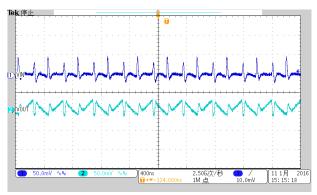
Ripple 1X Flash 800mA



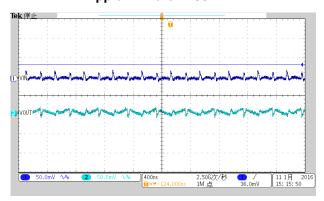
Ripple 1X Torch 250mA



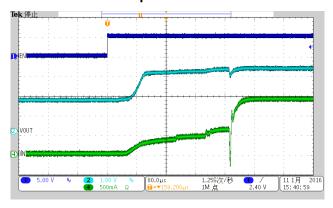
Ripple 2X Flash 800mA



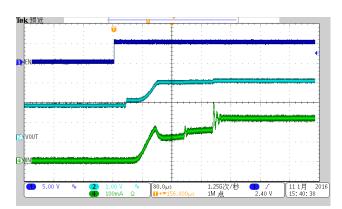
Ripple 2X Torch 250mA



Startup 800mA Flash

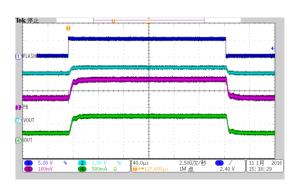


Startup 250mA Torch

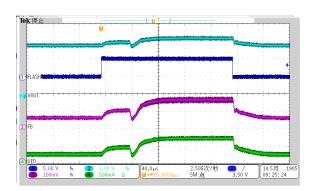




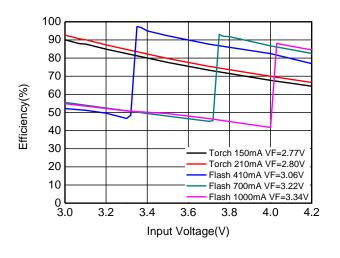
Torch in 1X to Flash in 1X Mode



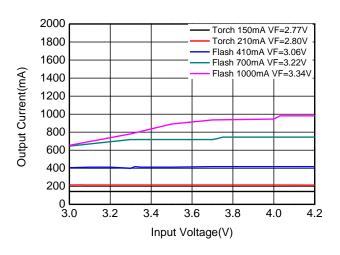
Torch in 1X to Flash in 2X Mode



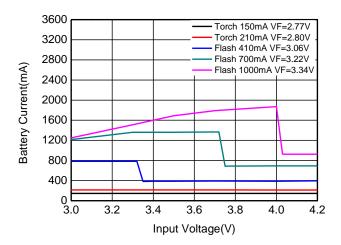
Efficiency vs. Input Voltage



Output Current vs. Input Voltage



Battery Current vs. Input Voltage





Operation Information

The WD3609DC is a charge pump regulator designed for converting a Li-lon battery voltage of 2.7V to 4.2V to drive a white LED used in digital still camera Flash and Torch applications. Flash mode of WD3609DC is usually used with a pulse about 1.2 seconds to generate a high intensity Flash. Torch of WD3609DC can be used continuously at a lower output current than Flash and is often used for several seconds in a digital still camera "movie" mode.

The WD3609DC also has two modes of operation to control the output current: the 1X mode and 2X mode. Operation begins after the enable pin EN receives a logic high, and then WD3609DC goes through a soft-start mode designed to reduce inrush current. The WD3609DC starts in the 1X mode, which acts like a linear regulator to control the output current by continuously monitoring the feedback pin FB. In 1X mode, as FB pin is below the regulation point, the WD3609DC automatically switches to the 2X mode. The WD3609DC remains in the 2X mode until one of four things happens:

- 1) The enable pin EN has been toggled.
- 2) The Flash pin has changed from high to low.
- 3) VIN is cycled or VIN recovers
- 4) A thermal fault occurs.

The 2X mode is the charge pump mode where the output can be pumped as high as two times the input voltage, provided the output does not exceed the maximum voltage for the WD3609DC, which is internally limited to about 5.5V. In the 2X mode, as in the 1X mode, the output current is regulated by the voltage at the FB pin.

In the Torch mode, (Flash = "GND") the Flash pin is set to logic low and the WD3609DC FB pin regulates to typical 50mV output:

V_{FB} = 50mV (Torch Mode)

When in Flash mode, (Flash = "High"), the FB regulation voltage is set by the resistor R_{SET} connected between the R_{SET} pin and SGND and the equation:

$$V_{FB} = (1.26 \text{V} / \text{R}_{SET}) \times 11.2 \text{k}\Omega \text{(Flash Mode)}$$

The output current is then set in either Flash or Torch mode by the equation:

$$I_{OUT} = V_{FB} / R_{SENSE}$$

Typical values of R_{SET} are $82k\Omega$ to $150k\Omega$ for a range of VFB = 177mV to 93mV in Flash mode

Apr, 2016 - Rev. 1.1



Application Information

Flash timeout protection

Due to the high currents typically available in Flash mode, it is necessary to protect the white LED from damage if left on too long. The WD3609DC has a timeout in Flash mode of approximately 1.2 seconds after which it will shut down operation. Operation will not begin again in Flash mode until the Enable pin or Flash pin have been set Low and then High again.

Over Temperature Protection

When the temperature of WD3609DC rises above 150° C, the over temperature protection circuitry turns off the output switches to prevent damage to the device. If the temperature drops back down below 135° C, the part automatically recovers and executes a soft start cycle.

Over Voltage Protection

The WD3609DC has over voltage protection. If the output voltage rises above the 5.5V threshold, the over voltage protection shuts off all of the output switches to prevent the output voltage from rising further. When the output decreases below 5.3V, the device resumes normal operation.

Over Current Protection

The over current protection circuitry monitors the average current out of the V_{OUT} pin. If the average output current exceeds approximately 1.2Amp, then the over current protection circuitry shuts off the output switches to protect the chip.

Brightness Control Using PWM

Dimming control can be achieved by applying a PWM control signal to the EN pin. The brightness of the white LEDs is controlled by increasing and decreasing the duty cycle of the PWM signal. While the operating frequency range of the PWM control is from 60Hz to 700Hz, the recommended maximum brightness frequency range of the PWM signal is

from 60Hz to 200Hz. A repetition rate of at least 60Hz is required to prevent flicker.

Component Selection

The WD3609DC charge pump circuit requires 3 capacitors (recommended values): 4.7µF input, 4.7μF output and 1μF flying capacitors. For the input capacitor, a larger value of 10µF will help reduce input voltage ripple for applications sensitive to ripple on the battery voltage. All the capacitors should be surface mount ceramic for low lead inductance necessary at the 2.4MHz switching frequency of the WD3609DC and to obtain low ESR, which improves bypassing on the input and output and improves output voltage drive by reducing output resistance. Ceramic capacitors with X5R or X7R temperature grade are recommended for most applications. Α selection of recommended capacitors included in below table:

Part Number	Capacitance	CapacitorSize	ESR
	/voltage	/Туре	@100
		/Thickness	K
C1005X5R0I105M	1uF/6.3V	0402/X5R/0.5mm	0.03
C1608X5R0J475K	4.7uF/6.3V	0603/X5R/0.9mm	0.02
C2012X5R0J106M	10uF/6.3V	0805/X5R/1.35mm	0.02
GRM155R60J105KE19B	1uF/6.3V	0402/X5R/0.55mm	0.03
GRM188R60J475KE19	4.7uF/6.3V	0603/X5R/0.9mm	0.02
GRM21BR60J106KE19L	10uF/6.3V	0805/X5R/1.35mm	0.02

The input and output capacitors should be located as close to the V_{IN} and V_{OUT} pins as possible to obtain best bypassing, and the returns should be connected directly to the PGND pin or to the thermal pad ground located under the WD3609DC. The flying capacitor should be located as close to the C1 and C2 pins as possible. To obtain lower output ripple, the C_{OUT} value can be increased from 1µF to 2.2µF or 4.7µF with a corresponding decrease in output ripple. For output currents of 500mA to 800mA, the recommended C_F flying capacitor value of 1µF should be used.

Resistor Selection

The sense resistor R_{SENSE} is determined by the value needed in the Torch mode for the desired output current by the equation:

 $R_{SENSE} = V_{FB}/I_{OUT}$ where $V_{FB} = 50mV$ (Torch Mode).



Once the R_{SENSE} resistor has been selected for Torch mode, the V_{FB} voltage can be selected for Flash mode using the following equation:

 $V_{FB} = I_{OUT} \times R_{SENSE}$ (Flash Mode) where I_{OUT} is for Flash Mode.

Next, the R_{SET} resistor can be selected for Flash mode using the following equation:

$$R_{SET} = (1.26V/VFB)x11.2k\Omega(Flash Mode)$$

For an example of 200mA Torch mode and 800mA Flash mode, the values R_{SENSE} = 0.25 $\Omega,\ V_{\text{FB}}$ = 150mV (Flash, Mode), and R_{SET} = 93k Ω are calculated. The power, obtained in the Flash mode

would be:

$$P_{FLASH} = V_{FB} \times I_{OUT} = 150 \text{mV} \times 800 \text{mA} = 90 \text{mW}$$

The typical 0603 surface mount resistor is rated 1/10, Watt continuous power and 1/5 Watt pulsed power, more than enough for this application. For other applications, the P_{FLASH} power can be calculated and resistor size selected. The R_{SENSE} resistor is recommended to be size 0603 for most applications. The range of typical resistor values and sizes are shown in below table:



Reference R_{SET} Resistor:

Part Reference Value		Toloronoo	Package Flash Current (mA) @ R _{SENSE} =				=	
Part Reference	(Ω)	Tolerance	Size	0.22Ω	0.27 Ω	0.33 Ω	0.39 Ω	0.47 Ω
R _{SET}	75K	5%	0402	850	692	566	479	397
R _{SET}	82K	5%	0402	777	633	518	438	363
R _{SET}	91K	5%	0402	700	570	466	394	327
R _{SET}	100K	5%	0402	636	518	424	358	297
R _{SET}	120K	5%	0402	531	433	354	300	248
R _{SET}	140K	5%	0402	457	370	303	256	212
R _{SET}	150K	5%	0402	422	343	281	238	197

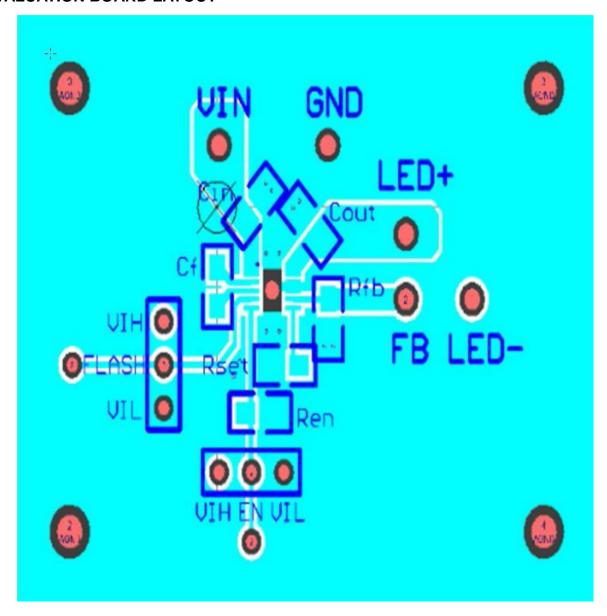
Reference R_{SENSE} Resistor:

Part Reference	Value (Ω)	Tolerance	Package Size	Torch Current (mA)
R _{SENSE}	0.22	5%	0603	227
R _{SENSE}	0.27	5%	0603	185
R _{SENSE}	0.33	5%	0603	151
R _{SENSE}	0.39	5%	0603	128
R _{SENSE}	0.47	5%	0603	106

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EVALUATION BOARD LAYOUT



Printed Circuit Board Layout Recommendations

Follow the PCB layout guidelines for optimal performance:

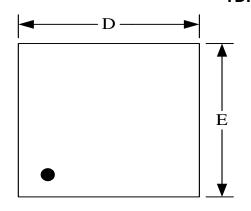
- 1. Place the flying capacitor CF as close to the chip as possible as possible; otherwise 2x mode performance will be compromised. Also keep analog components away from this capacitor.
- 2. Place input and output decoupling capacitors as close to the chip as possible to reduce switching noise and output ripple.
- 3. The power traces, consisting of the VIN/GND trace, the VOUT trace and the WLED trace should be kept short and wide. Also minimize the feedback loop area (consisting of WLED/FB) small.
- 4. Connect the exposed pad to the GND plane to achieve the best power dissipation.

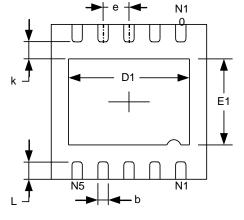
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Package outline dimensions

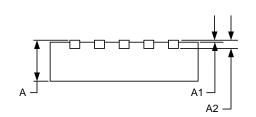
TDFN3x3-10L

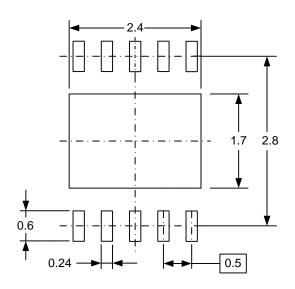




TOP VIEW

BOTTOM VIEW





SIDE VIEW

RECOMMENDED LAND PATTERN (Unit:mm)

	Dimensions		Dimensions		
SYMBOL	In In	ches	In Inches		
	Min	Max	Min	Max	
Α	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
A2	0.203REF		0.008REF		
D	2.900	3.100	0.114	0.122	
D1	2.300	2.500	0.091	0.098	
E	2.900	3.100	0.114	0.112	
E1	1.600	1.800	0.063	0.071	
k	0.200MIN		0.008	BMIN	
b	0.180	0.300	0.007	0.012	
е	0.500TPY		0.020	TYP	
L	0.300	0.500	0.012 0.020		